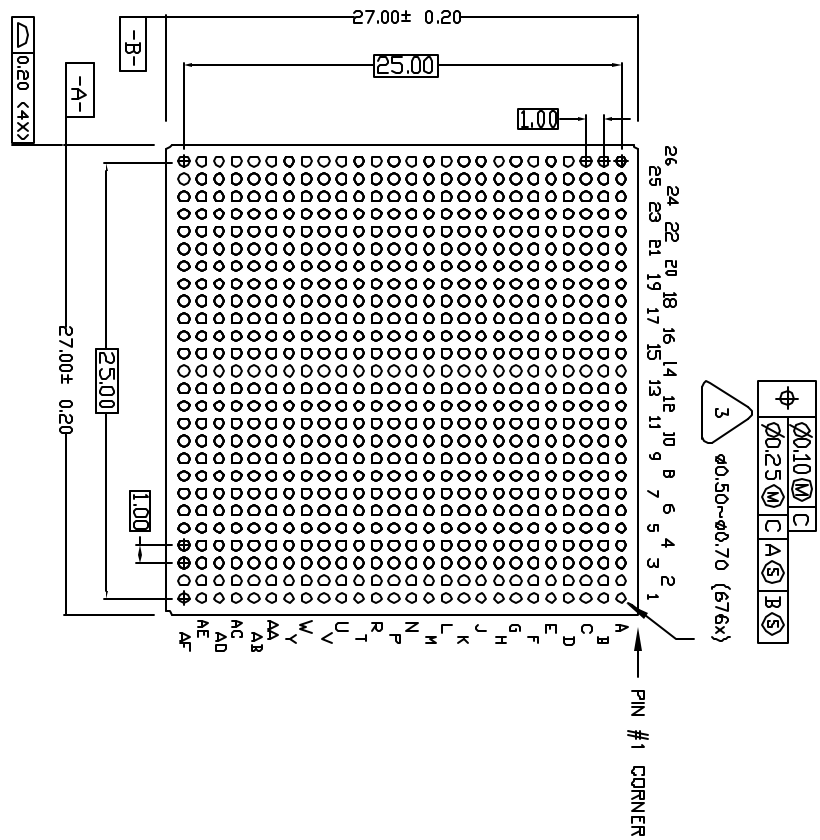
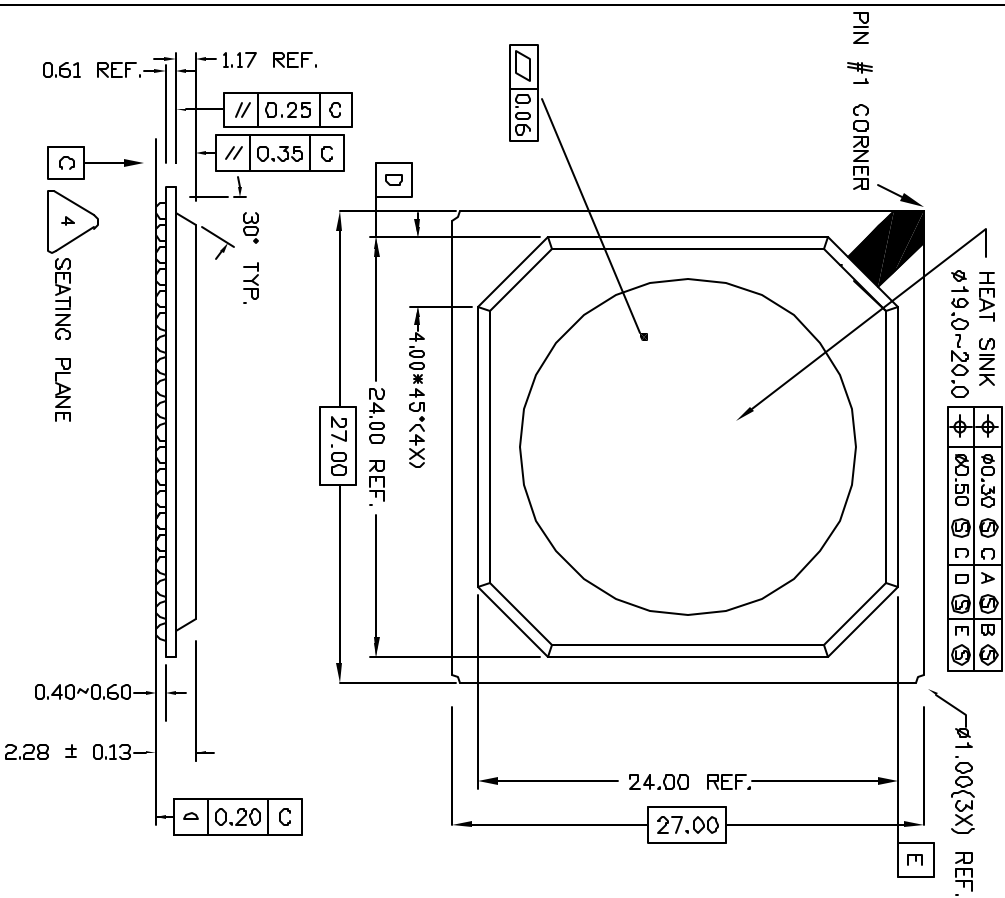


REVISIONS			
LR	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING	03/04	



- NOTES:
1. DIMENSIONS ARE IN MILLIMETERS
 2. ALL DIMENSIONS AND TOLERANCE CONFORM TO ASME Y 14.5M-1994
 3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
 4. PRIMARY DATUM C AND SEATING PLANES ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

SIGNATURE		DATE		TITLE	
DOC. CONTROL:				MARKETING OUTLINE, 676 LEAD, TEPBGA (27X27)	
ENGR. WORK:				1.00 MM PITCH, 2.28 MM THICK, 4 LAYER (WITH HEAT SINK)	
MFG. ENGR:				SIZE	FORM NO
CHECKED BY:	SATYA C.	03/04		A	
DRAWN BY:	JFD	03/04		PART NO	56-G6029-002
				SCALE	NONE
				SHEET	1 OF 1



REV A